IN THE CLAIMS

Current Listing Of Claims:

1.-12. (Cancelled)

13. (Currently Amended) An electroless plating structure on a metal-six copper (M6 Cu) pad, having a composition comprising:

$pM_w\,sM_x\,B_y\,P_z$

wherein pM is a primary metal selected from at least one of Cu, Ag, Au, ~~Co,~~ Pd, Pt, Ni, Rh, and Ir;

wherein sM is a secondary metal selected from zero to at least one of Cr, Mo, W, Mn, Tc, and Re;

wherein B and P represent boron and phosphorus, respectively; and

wherein w has a range from about 0.5 to about 0.99, x has a range from about 0.0 to about 0.2, y has a range from about .01 to about 0.1, and z has a range from ~~about~~ 0.0 to about 0.02.

14. (currently amended) The electroless plating structure according to claim 13, ~~further including~~wherein the composition of $pM_w\,sM_x\,B_y\,P_z$ ~~a metal compound~~ is selected from the group consisting of: ~~Cu~~pMB, ~~Cu~~pMBP, ~~Cu~~pMCrB, ~~Cu~~pMCrBP, ~~Cu~~pMMoB, ~~Cu~~pMMoBP, ~~Cu~~pMWB, ~~Cu~~pMWBP, ~~Cu~~pMMnB, ~~Cu~~pMMnBP, ~~Cu~~pMTcB, ~~Cu~~pMTcBP, ~~Cu~~pMReB, ~~Cu~~pMReBP, ~~Cu~~pMNiB, ~~Cu~~pMNiBP, ~~Cu~~pMNiCrB, ~~Cu~~pMNiCrBP, ~~Cu~~pMNiMoB, ~~Cu~~pMNiMoBP, ~~Cu~~pMNiWB, ~~Cu~~pMNiWBP, ~~Cu~~pMNiMnB, ~~Cu~~pMNiMnBP, ~~Cu~~pMNiTcB, ~~Cu~~pMNiTcBP, ~~Cu~~pMNiReB, and ~~Cu~~pMNiReBP.

15. (currently amended) The electroless plating structure according to claim 14, wherein pM~~Cu is substituted or accompanied by~~ comprises at least one of Cu, Ag and Au.

16. (currently amended) The electroless plating structure according to claim 13, ~~further including~~wherein the composition of $pM_w sM_x B_y P_z$ ~~a metal compound~~ is selected from the group consisting of: ~~Nip~~MB, ~~Nip~~MBP, ~~Np~~MCrB, ~~Nip~~MCrBP, ~~Nip~~MMoB, ~~Nip~~MMoBP, ~~Nip~~MWB, ~~Nip~~MWBP, ~~Nip~~MMnB, ~~Nip~~MMnBP, ~~Nip~~MTcB, ~~Nip~~MTcBP, ~~Nip~~MReB, ~~Nip~~MReBP~~, NiCoB, NiCoBP, NiCoCrB, NiCoCrBP, NiCoMoB, NiCoMoBP, NiCoWB, NiCoWBP, NiCoMnB, NiCoMnBP, NiCoTcB, NiCoTcBP, NiCoReB, and NiCoReBP~~.

17. (currently amended) The electroless plating structure according to claim 16, wherein pM~~Ni is substituted or accompanied by~~ comprises at least one of Ni, Pd and Pt.

18. (currently amended) The electroless plating structure according to claim 13, ~~further including~~wherein the composition of $pM_w sM_x B_y P_z$ ~~a metal compound~~ is selected from the group consisting of: ~~CoB, CoBP, Cop~~MCrB, ~~CoCrBP, CoMoB, CoMoBP, CoWB, CoWBP, Cop~~MMnB, ~~CoMnBP, Cop~~MTcB, ~~CoTcBP, Cop~~MReB, ~~CoReBP, Ni Cop~~MB, ~~CoPdBP, Cop~~MPdCrB, ~~CoPdCrBP, Cop~~MPdMoB, ~~CoPdMoBP, Cop~~MPdWB, ~~CoPdWBP, Cop~~MPdMnB, ~~CoPdMnBP, Cop~~MPdTcB, ~~CoPdTcBP, Co~~and pMPdReB~~, and CoPdReBP~~.

19. (currently amended) The electroless plating structure according to claim 18, wherein pM~~Co is substituted or accompanied by~~ comprises at least one of Co, Rh and Ir.

20. (currently amended) The electroless plating structure according to claim 13, wherein the primary metal is a metal combination selected from cobalt-nickel, cobalt-nickel-silver, cobalt-nickel-silver-copper, cobalt-silver, cobalt-silver-copper, cobalt-copper, cobalt-copper-nickel, nickel-silver, nickel-silver-copper, nickel-copper, and silver-copper.

21. (original) The electroless plating structure according to claim 13, wherein the primary metal is selected from MP, MB, MPB, MW, MWP, MWBP, MNiP, MNiWP, MReP, MReBP, and wherein M is a metal combination selected from cobalt-nickel, cobalt-nickel-silver, cobalt-nickel-silver-copper, cobalt-silver, cobalt-silver-copper, cobalt-copper, cobalt-copper-nickel, nickel-silver, nickel-silver-copper, nickel-copper, and silver-copper.

22. (New) The electroless plating structure according to claim 13, wherein the composition of $pM_w\,sM_x\,B_y\,P_z$ is selected from the group consisting of: CoRhB, CoIrB, CoRhIrB, CoRhMoB, CoIrMoB, CoRhIrMoB, CoRhWB, CoIrWB, and CoRhIrWB.

23. (New) An electroless plating structure on a conductive pad, having a composition comprising:

$$pM_w\,sM_x\,B_y\,P_z$$

wherein pM is a primary metal selected from at least one of Cu, Ag, Au, Co, Pd, Pt, Ni, Rh, and Ir;

wherein sM is a secondary metal selected from zero to at least one of Cr, Mo, W, Mn, Tc, and Re;

wherein B and P represent boron and phosphorus, respectively; and

wherein w has a range from about 0.5 to about 0.99, x has a range from about 0.0 to about 0.2, y has a range from about .01 to about 0.1, and z has a range from a value approaching but not equal to 0.0 to about 0.02.

24. (new) The electroless plating structure according to claim 23, wherein the composition of $pM_w\ sM_x\ B_y\ P_z$ is selected from the group consisting of: pMBP, pMCrBP, pMMoBP, pMWBP, pMMnBP, pMTcBP, pMReBP, pMPdBP, pMPdCrBP, pMPdMoBP, pMPdWBP, pMPdMnBP, pMPdTcBP, and pMPdReBP.

25. (new) The electroless plating structure according to claim 24, wherein pM comprises at least one of Co, Rh and Ir.

26. (New) An electroless plating structure on a conductive pad, having a composition comprising:

$Co_w\ sM_x\ B_y\ P_z$

wherein sM is a secondary metal selected from zero to at least one of Cu, Ag, Au, Pd, Pt, Ni, Rh, Ir, Cr, Mn, and Tc;

wherein Co, B and P represent cobalt, boron and phosphorus, respectively; and

wherein w has a range from about 0.5 to about 0.99, x has a range from about 0.0 to about 0.2, y has a range from about .01 to about 0.1, and z has a range from a value approaching but not equal to 0.0 to about 0.02.

27. (new) The electroless plating structure of claim 26 wherein the composition of $Co_w sM_x B_y P_z$ is selected from the group consisting of: sMCoB, sMCoBP, sMCoCrB, sMCoCrBP, sMCoMoB, sMCoMoBP, sMCoWB, sMCoWBP, sMCoMnB, sMCoMnBP, sMCoTcB, sMCoTcBP, sMCoReB, and sMCoReBP.

28. (new) The electroless plating structure according to claim 27, wherein sM comprises at least one of Ni, Pd and Pt.